2023-06-08 Contact Name Title - Contact Phone - Contact* Email - Contact* Product-Env-Stewards Authorized Representative* Phone - Representative* Email - Representative* Email - Representative*	IPC ASSOCIATION CONNECTED FOR THE PROPERTY OF	© Copyright 2005. IP	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with low level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.										
Company name* Company unique ID Unique ID Authority Response Date* 2023-06-08 Contact Name Contact Name Contact Name Contact Env-Stewards Contact Env-St	752-21.1						e *					rials and I	Mfg Information	on		
nsemi ontact Name Title - Contact Product-Env-Stewards Product-Env-Stewards Product-Enviro Compliance Title - Representative Product-Env-Stewards Product-Env-Stewards Product-Enviro Compliance Title - Representative Phone - Representative* Phone - Representative* Product-Env-Stewards Product-Env-Stewards Product-Enviro Compliance NA Product-Env-Stewards@onsemi.com Requester Item Number Mfr Item Number Mfr Item Name Effective Date Version Manufacturing Site Weight* UOM MC78M05ACTG ANA 500MA 5V VREG 2023-06-08 MY1 1962.0 mg Manufacturing Proccess Information Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycl Matte Tin (Sn) - annealed CU Alloy NA 0 C 30 seconds 3	upplier Info	rmation														
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or more information regarding material composition please refer to page 3			•,•	1 0 .												

RoHS Material Composition Declaration			Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive Company acknowledges that Supplier may have relied on informationprovided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier nenter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's Itaalian agreement, the warranty rights and/or remedies of Supplier's Standard Terms and Conditions										
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted substance	es per the definition above except for selected exemp	otions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.										
Supplier Digital Signature Ra	astislav Drska	-6_								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	3.55	mg	Supplier	Silicon (Si)	7440-21-3		3.55	mg
Die Attach	82.92	mg	A	Lead (Pb)	7439-92-1	7a	78.774	mg
			Supplier	Tin (Sn)	7440-31-5		4.146	mg
Lead Frame	1299.13	mg	В	Nickel (Ni)	7440-02-0		0.6496	mg
			Supplier	Iron (Fe)	7439-89-6		1.2991	mg
			Supplier	Copper (Cu)	7440-50-8		1296.7916	mg
			Supplier	Phosphorus (P)	7723-14-0		0.3896	mg
Mold Compound-Black	543.9	mg		Phenolic Resin	proprietary data		32.634	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		54.39	mg
			Supplier	Carbon Black (C)	1333-86-4		2.7195	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		40.7925	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		413.364	mg
Plating	31.13	mg	Supplier	Tin (Sn)	7440-31-5		31.13	mg
Wire Bond - Cu	1.37	mg	Supplier	Copper (Cu)	7440-50-8		1.37	mg